

NIKAFLEX®

聚酰亚胺基材覆盖膜
Polyimide film base coverlay

CISA

特点 Features

- 1** 焊锡耐热性优良、能充分承受流焊工序、可广泛用于各种电子设备部件。
 Because of excellent resistance to solder temperature, it bears up against flow-soldering process and is used consequently for a wide range of parts of high-class electronic equipment.
- 2** 长期耐热性优良、粘合剂变色较少。
 Excellent heat resistance for a long period of time and less discoloration of adhesive.
- 3** 耐迁移性优异。
 Excellent ion migration resistance.
- 4** 低反弹。
 Least repellency.

标准产品规格 Specifications of standard Products

基材薄膜厚度 (μm) Thickness of Base Film		12.5, 25, 50
粘合剂 Adhesive	种类 Classification	热硬化性树脂 Thermosetting Resin
	厚度 (μm) Thickness	15, 25, 35
离型材料 Releasing Material on Adhesive Surface		离型纸 Release Paper
标准尺寸 (mm) Standard Size		500 × Roll (100m)

UL FILE No:E46785

使用注意事项 Caution

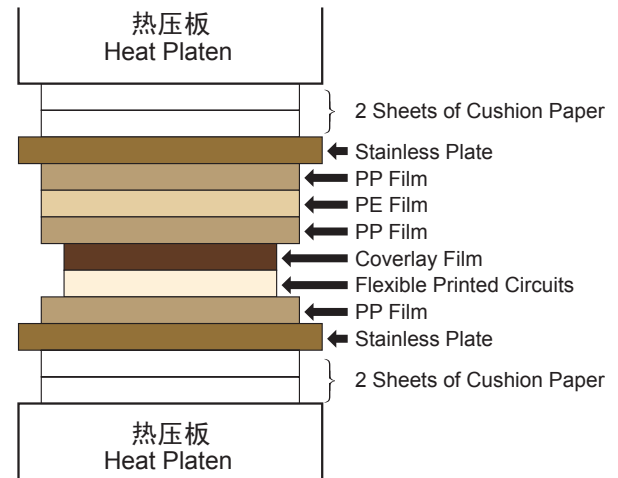
- 1** 粘合剂为半固化状态、如果放置在常温条件下、会加速粘合剂的硬化。因此请在低温（5℃以下）且湿度低于 80% 的条件下进行保管。
 Time and temperature rapidly promote a change from the semicured to the fully cured adhesive state, so keep coverlays at 5°C or below and at 80%RH or below.
- 2** 质量保证期限为生产后未开封状态下 6 个月。
 Guaranteed period for CISA before unpacked is 6 months On the above keeping condition after manufacture.
- 3** 用纸作为压合垫材时、纸中的水分会使粘合剂质量劣化、有时会导致粘合剂和薄膜剥离、使用前请确认。
 Moisture in press pads mode of paper might make adhesiveness weaker and cause delamination of adhesive and polyimide film. If paper is used as press pads, be sure to check the condition of press pads paper before using that paper.

加工方法示例 An Example of Processing Method

压合步骤 Procedures (Press-Bonding)

- 1** 常温下设置
Setting at room temp.
- 2** 抽真空 5次左右
Removing Air (about 5 times)
- 3** 加压 (2 ~ 4MPa)
Apply pressure (2 to 4 MPa)
- 4** 升温
Temp. Elevation
- 5** 升温至 100°C时再次抽真空
Removing Air again at 100°C
- 6** 加压 (2 ~ 4MPa)
Apply pressure (2 to 4 MPa)
- 7** 升温至 140 ~ 160°C时再次抽真空
Removing Air again at 140 to 160°C
- 8** 在 140 ~ 160°C、2 ~ 4MPa 状态下保持 40 ~ 60 分钟
Press-bonding at 140 ~ 160°C under pressure of 2 ~ 4MPa for 40 to 60 min.
- 9** 冷却 Cooling
- 10** 取出 Taking out

压合设置示例 Materials assembly for Press-bonding



CISA 特性表 Properties of CISA

聚酰亚胺薄膜 25 μm、粘胶厚度 35 μm、CISA 2535 (DB)
Model No. CISA 2535 (DB) (Polyimide Film 25μm, Adhesive 35μm)

试验项目 Test item	单位 Unit	处理条件 Treatment conditions	标准值 (平均) Our Standard Value (Average)	保证值 (平均) Guaranteed Value (Average)	试验方法 Test Method
粘胶流动性 Resin Flow	mm	A	0.18	0.20 以下 (Max.)	本公司方式 Our Standard
表面电阻率 Surface Resistivity	Ω	C-96/20/65	3×10^{14}	5.0×10^{10} 以上 (Min.)	JIS C 6481
		C-96/40/90	8×10^{13}	1.0×10^{10} 以上 (Min.)	
体积电阻率 Volume Resistivity	Ω-cm	C-96/20/65	1×10^{15}	1.0×10^{12} 以上 (Min.)	JIS C 6471
		C-96/40/90	5×10^{14}	5.0×10^{10} 以上 (Min.)	
剥离强度 Peel Strength	N/mm	A	0.7	0.6 以上 (Min.)	JPCA-BM-02
		E-1/180	0.7	0.6 以上 (Min.)	
焊锡耐热性 Solder Heat Resistance	—	280°C /10sec.	无异常 No change in appearance	不得发生膨胀或剥离 No delamination and blister	IPC-FC-232B
耐热性 Heat Resistance	—	E-24/130	无异常 No change in appearance		JIS C 6481
耐药品性 Chemical Resistance	—	23°C /10min	无异常 No change in appearance		JPCA-BM-02

Note (1) 粘胶流动性、剥离强度、焊锡耐热性、耐热性、耐药品性是 将 35 μm 电解铜箔 (1 盎司) 的光泽面和粘合剂面贴合层压后获得的值。
Values of resin flow, peel strength, solder resistance, heat resistance and chemical resistance are those of laminate obtained by press-bonding the shiny side of electrolytic copper foil (35μm, 1 ounce) with CISA2535 (PB).

(2) 压合条件 / 温度: 160°C、时间: 40 分钟、成型压力: 4MPa
Press conditions: 160°C/40min./molding pressure 4MPa